### UNITED STATES SECURITIES AND EXCHANGE COMMISSION

Washington, D.C. 20549

# FORM 8-K

### **CURRENT REPORT** Pursuant to Section 13 or 15(d) of The Securities Exchange Act of 1934

Date of Report (Date of earliest event reported): April 1, 2020

# **Transphorm, Inc.** (Exact name of registrant as specified in its charter)

000-55832

82-1858829

Delaware

(State or Other Jurisdiction	(Commission	(I.R.S. Employer
of Incorporation)	File Number)	Identification No.)
	75 Castilian Drive	
	Goleta, CA 93117	
(Address	s of principal executive offices, including zip	p code)
	(805) 456-1300	
(Regi	istrant's telephone number, including area co	ode)
	Not Applicable	
(Former 1	name or former address, if changed since last	t report)
Check the appropriate box below if the Form 8-K filing i following provisions:	is intended to simultaneously satisfy the filin	ng obligation of the registrant under any of the
$\hfill \square$ Written communications pursuant to Rule 425 under t	the Securities Act (17 CFR 230.425)	
$\hfill \square$ Soliciting material pursuant to Rule 14a-12 under the	Exchange Act (17 CFR 240.14a-12)	
$\square$ Pre-commencement communications pursuant to Rule	e 14d-2(b) under the Exchange Act (17 CFR	240.14d-2(b))
$\square$ Pre-commencement communications pursuant to Rule	e 13e-4(c) under the Exchange Act (17 CFR	240.13e-4(c))
Securities registered pursuant to Section 12(b) of the Act	:: None	
Indicate by check mark whether the registrant is an emer Rule 12b-2 of the Securities Exchange Act of 1934 (17 C		5 of the Securities Act of 1933 (17 CFR§230.405) o
Emerging growth company $oxtimes$		
If an emerging growth company, indicate by check mark or revised financial accounting standards provided pursu	_	

#### **Item 8.01 Other Events**

As previously disclosed by Transphorm, Inc. ("Transphorm") in its Current Report on Form 8-K filed on February 14, 2020, the Company is party to a joint venture agreement (the "JV Agreement") with Fujistu Semiconductor Limited ("FSL") for the ownership and operations of Aizu Fujitsu Semiconductor Wafer Solutions ("AFSW"), a wafer fabrication facility located in Aizu Wakamatsu, Japan. Transphorm currently holds a 49% interest in AFSW.

On April 1, 2020, FSL exercised its put option under the JV Agreement and notified Transphorm that FSL intended to exit the joint venture by selling its 51% interest in AFSW to Transphorm. Under the terms of the JV Agreement, the aggregate purchase price for FSL's interest in AFSW is expected to be one Japanese Yen. While the JV Agreement provides that completion of the transaction shall take place as soon as sixty (60) days from the date of the exercise notice, the Company expects such transaction will be subject to regulatory and other approvals in Japan, which the Company makes no assurance will be obtained.

# Signature

Pursuant to the requirements of the Securities Exchange Act of 1934, the registrant has duly caused this report to be signed on its behalf by the undersigned hereunto duly authorized.

Transphorm, Inc.

Dated: April 7, 2020 By: /s/ Mario Rivas

Mario Rivas

Chief Executive Officer